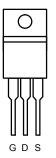


N-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)			
200	0.058at V _{GS} = 10 V	35			

TO-220AB

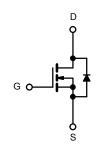


FEATURES

- TrenchFET[®] Power MOSFETS
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

Industrial



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	200	V		
Gate-Source Voltage	V _{GS}	± 20	V		
Continuous Drain Current (T ₁ = 175 °C)	T _C = 25 °C	1	35		
Continuous Drain Current (1j = 175°C)	T _C = 125 °C	I _D	23		
Pulsed Drain Current	I _{DM}	70	- A		
Avalanche Current	I _{AR}	35			
Repetitive Avalanche Energy ^a	L = 0.1 mH	E _{AR}	61	mJ	
	T _C = 25 °C	D	300 ^b	14/	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	– P _D –	3.75	- W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W
Junction-to-Case (Drain)	R _{thJC}	0.5	C/W

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR-4 material).



Deremeter	Symbol	Test Conditions	Min	Тур.	Mox	4: مرا ا	
Parameter Static	Symbol	Test Conditions	Min .	Typ.	Max.	Unit	
	V _{DS}	V _{DS} = 0 V, I _D = 250 µA	200	1			
Drain-Source Breakdown Voltage		50 5 .			4	V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 30 V$			± 250	nA	
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$				50 µA	
		$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \! \geq \! 5$ V, V_{GS} = 10 V	70			A	
		V _{GS} = 10 V, I _D = 20 A		0.058			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V_{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.130		Ω	
	• •DS(on)	V_{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.170			
		V _{GS} = 6 V, I _D = 15 A		0.070			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		70		S	
Dynamic ^b				•			
Input Capacitance	C _{iss}			2690		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		200			
Reverse Transfer Capacitance	C _{rss}			110			
Total Gate Charge ^c	Qg			95	140	nC	
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 100 V, V_{GS} = 10 V, I_{D} = 45 A		28			
Gate-Drain Charge ^c	Q _{gd}			34			
Gate Resistance	R _g	f = 1 MHz		1.6		Ω	
Turn-On Delay Time ^c	t _{d(on)}			22	35		
Rise Time ^c	t _r	V _{DD} = 100 V, R _L = 2.78 Ω		220	330		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 45 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 2.5 \Omega$		40	60	ns	
Fall Time ^c	t _f	, ř		145	220		
Source-Drain Diode Ratings and Cha	racteristics (T _C = 25 °C) ^b		I			
Continuous Current	Is				45		
Pulsed Current	I _{SM}				70	A	
Forward Voltage ^a	V _{SD}	I _F = 45 A, V _{GS} = 0 V		1	1.5	V	
Reverse Recovery Time	t _{rr}			150	225	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 45 A, di/dt = 100 A/µs		12	18	A	
	Q _{rr}	1 / 1 - 1		0.9	2	μC	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

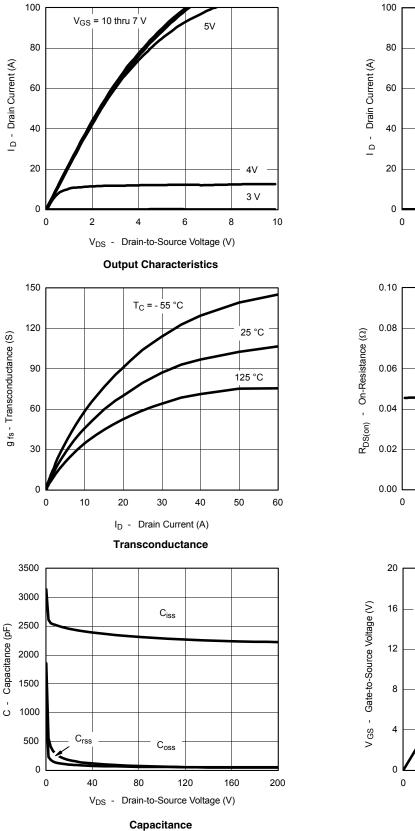
c. Independent of operating temperature.

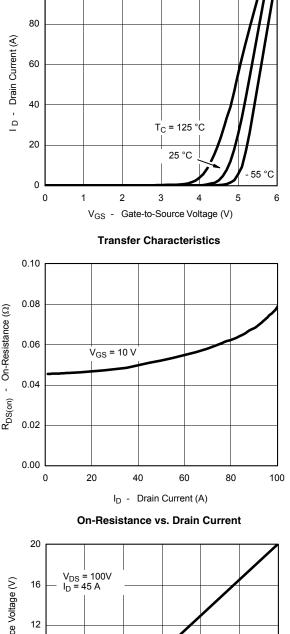
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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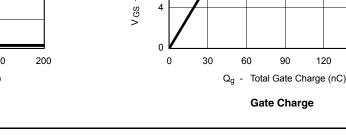








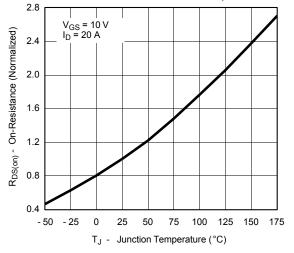
Gate Charge



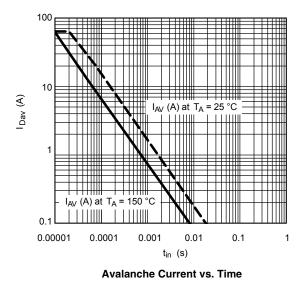
IPP320N20N3 G

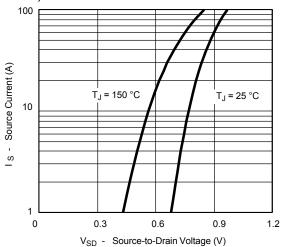


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

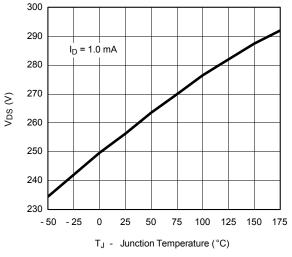


On-Resistance vs. Junction Temperature





Source-Drain Diode Forward Voltage

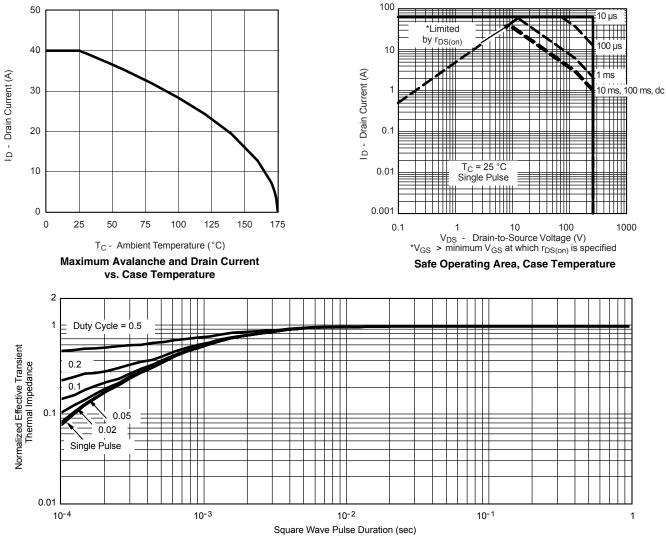


Drain Source Breakdown vs. Junction Temperature

IPP320N20N3 G



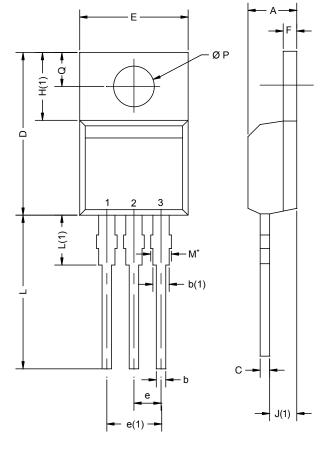
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



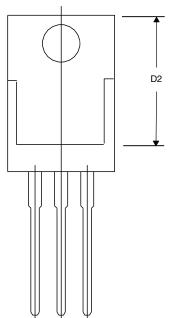
TO-220AB



	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
с	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

Note

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM





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